GND ∏ 10

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11 ∏ LE

DGV, DW, OR PW PACKAGE Operates From 1.65 V to 3.6 V (TOP VIEW) Max tpd of 3.3 ns at 3.3 V ±24-mA Output Drive at 3.3 V 20 🛮 V_{CC} OE 19 8Q **Bus Hold on Data Inputs Eliminates the** 1Q [**Need for External Pullup/Pulldown** 1D 🛮 3 18 8D Resistors 2D Π4 17 **∏** 7D 2Q Π 16 **∏** 7Q Latch-Up Performance Exceeds 100 mA Per 3Q 15 6Q JESD 78. Class II 3D **[**] 7 14 **∏** 6D **ESD Protection Exceeds JESD 22** 13 T 5D 4D **∏** 8 - 2000-V Human-Body Model (A114-A) 4Q 🛮 9 12 🛮 5Q 200-V Machine Model (A115-A)

description/ordering information

- 1000-V Charged-Device Model (C101)

This octal transparent D-type latch is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH373 is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	COIC DW	Tube	SN74ALVCH373DW	ALVOL1070
	SOIC - DW	Tape and reel	SN74ALVCH373DWR	ALVCH373
-40°C to 85°C	TSSOP - PW	Tape and reel	SN74ALVCH373PWR	VB373
-40 C to 65 C	TVSOP – DGV	Tape and reel	SN74ALVCH373DGVR	VB373
	VFBGA – GQN	Tape and reel	SN74ALVCH373GQNR	
	VFBGA – ZQN (Pb-free)	rape and reer	SN74ALVCH373ZQNR	VB373

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

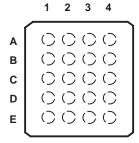


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GQN OR ZQN PACKAGE (TOP VIEW)



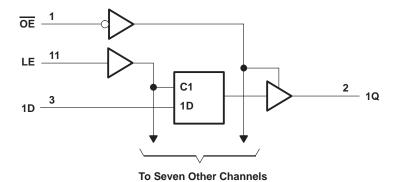
terminal assignments

	1	2	3	4
Α	1Q	ŌĒ	V _{CC}	8Q
В	2D	7D	1D	8D
С	3Q	2Q	6Q	7Q
D	4D	5D	3D	6D
Е	GND	4Q	LE	5Q

FUNCTION TABLE (each latch)

	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q ₀
Н	Χ	Χ	Z

logic diagram (positive logic)



Pin numbers shown are for the DGV, DW, and PW packages.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}		–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)		
Output voltage range, V _O (see Notes 1 and 2)		$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$)		
Output clamp current, I_{OK} ($V_O < 0$)		
Continuous output current, IO		
Continuous current through V _{CC} or GND		±100 mA
Package thermal impedance, θ _{JA} (see Note 3)	: DGV package	92°C/W
•	DW package	
	GQN/ZQN package	
	PW package	83°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 4.6 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		1.65	3.6	V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}		
V_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		8.0	
VI	Input voltage		0	Vcc	V
٧o	Output voltage		0	Vcc	V
		V _{CC} = 1.65 V		-4	
		V _{CC} = 2.3 V		-12	
ЮН	High-level output current	V _{CC} = 2.7 V		-12	mA
		V _{CC} = 3 V		-24	
		V _{CC} = 1.65 V		4	
	Landard constant	V _{CC} = 2.3 V		12	4
IOL	Low-level output current	V _{CC} = 2.7 V		12	mA
		V _{CC} = 3 V		24	
Δt/Δν	Input transition rise or fall rate	·		5	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS	Vcc	MIN	TYP [†]	MAX	UNIT
		I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} -0	.2		
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			
		I _{OH} = -6 mA	2.3 V	2			
∨он			2.3 V	1.7			V
		I _{OH} = -12 mA	2.7 V	2.2			
			3 V	2.4			
		I _{OH} = -24 mA	3 V	2			
		I _{OL} = 100 μA	1.65 V to 3.6 V			0.2	
		I _{OL} = 4 mA	1.65 V			0.45	
.,		I _{OL} = 6 mA	2.3 V			0.4	.,
VOL			2.3 V			0.7	V
		I _{OL} = 12 mA	2.7 V			0.4	
		I _{OL} = 24 mA	3 V			0.55	
Ц		V _I = V _{CC} or GND	3.6 V			±5	μΑ
		V _I = 0.58 V	1.65 V	25			
		V _I = 1.07 V	1.65 V	-25			
		V _I = 0.7 V	2.3 V	45			
l _l (hold)		V _I = 1.7 V	2.3 V	-45			μΑ
(/		V _I = 0.8 V	3 V	75			
		V _I = 2 V	3 V	-75			
		$V_1 = 0 \text{ to } 3.6 \text{ V}^{\ddagger}$	3.6 V			±500	
loz		$V_O = V_{CC}$ or GND	3.6 V			±10	μΑ
ICC		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V			20	μΑ
Δlcc		One input at V _{CC} – 0.6 V, Other inputs at V _C	CC or GND 3 V to 3.6 V			750	μΑ
	Control inputs		2.21		4.5		
Ci	Data inputs	V _I = V _{CC} or GND	3.3 V		5		pF
Со	Outputs	$V_O = V_{CC}$ or GND	3.3 V		7.5		pF

 $[\]uparrow$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V _{CC} =	1.8 V	V _{CC} =	2.5 V 2 V	V _{CC} =	2.7 V	V _{CC} =	3.3 V 3 V	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _W	Pulse duration, LE high	3.8		3.3		3.3		3.3		ns
t _{su}	Setup time, data before LE↓	1.3		0.5		0.5		0.5		ns
t _h	Hold time, data after LE \downarrow	0.5		1.3		1.7		1.2		ns



[‡] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

SN74ALVCH373 **OCTAL TRANSPARENT D-TYPE LATCH** WITH 3-STATE OUTPUTS SCES116G - JULY 1997 - REVISED AUGUST 2003

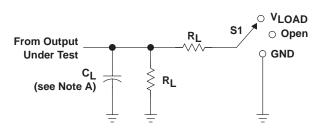
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	PARAMETER FROM (INPUT) (V _{CC} =		V _{CC} =		VCC =	2.7 V	V _{CC} =	3.3 V 3 V	UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
_	D	_	1.7	6.3	1	4		4	1	3.6	
^t pd	LE	Q	2	6.1	1	3.8		3.7	1	3.3	ns
^t en	ŌE	Q	3.4	8.3	1.9	5.4		5.4	1.6	4.8	ns
^t dis	ŌĒ	Q	1.6	7	1	4.4		4.4	1	4.4	ns

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V	UNIT	
	Power dissipation capacitance	Outputs enabled	C _L = 0,	31	33	37	
C _{pd}	per latch	Outputs disabled	f = 10 MHz	7	7	9	pF

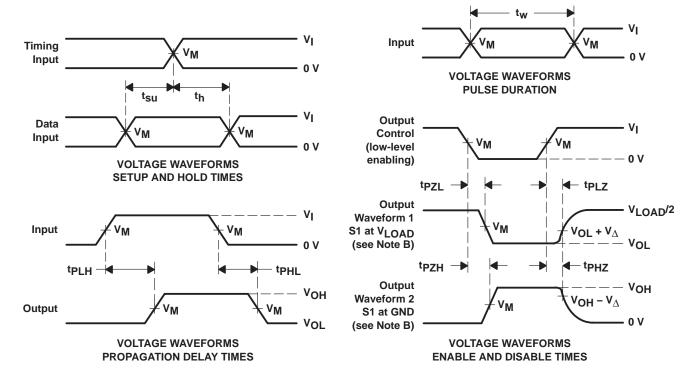
PARAMETER MEASUREMENT INFORMATION



TEST	S1
^t pd	Open
tPLZ ^{/t} PZL	V _{LOAD}
tPHZ ^{/t} PZH	GND

LOAD CIRCUIT

Wa a	IN	PUT	V	V	6	6	V
VCC	٧ _I	t _r /t _f	VΜ	VLOAD	CL	RL	$v_{\scriptscriptstyle\Delta}$
1.8 V ± 0.15 V	VCC	≤ 2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 \pm 0.2 V	VCC	≤ 2 ns	V _{CC} /2	2×VCC	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

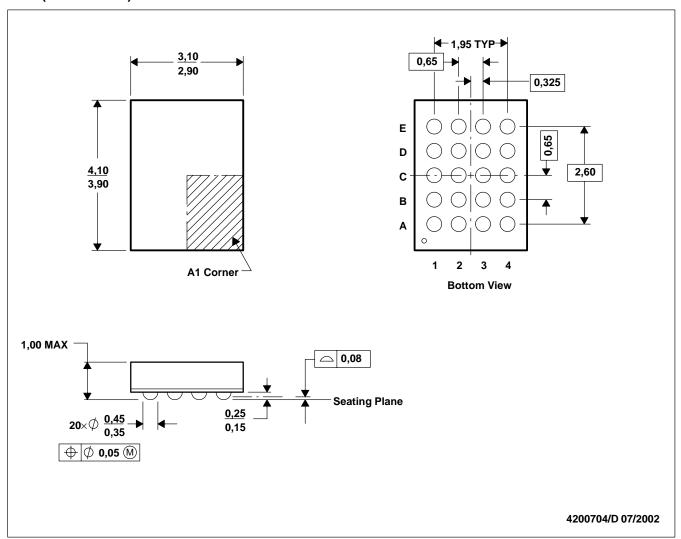
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzI and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



GQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. MicroStar Junior™ configuration

D. Falls within JEDEC MO-225 variation BC.

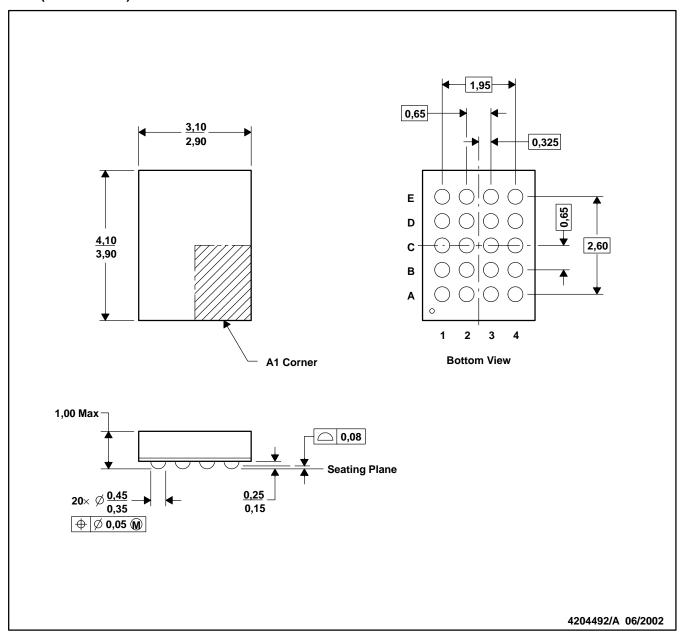
E. This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.

MicroStar Junior is a trademark of Texas Instruments.



ZQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. MicroStar Junior™ configuration.
 - D. Fall within JEDEC MO-225 variation BC.
 - E. This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead)SnPb).

MicroStar Junior is a trademark of Texas Instruments.



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

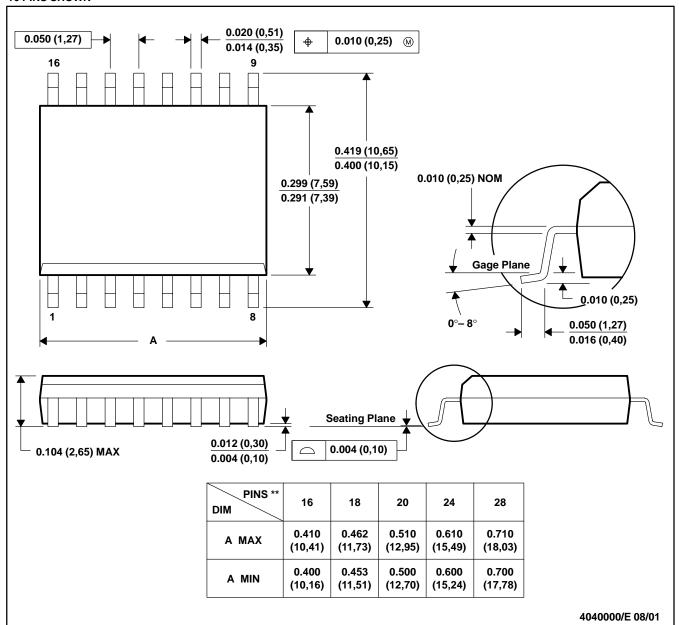
D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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